

High-Reliability

# Precision Die-Attach (PDA) Preforms

For Critical, High-Reliability Laser  
& RF Applications

- Highly accurate bondline thickness control
- Precision edge quality
- Flat, free of warping or bends
- Optimized cleanliness
- Default waffle pack
- Alloys available:
  - 80Au/20Sn      – 79Au/21Sn
  - 78Au/22Sn      – 75Au/25Sn
  - 82Au/18In      – 88Au/12Ge

Contact our engineers: [askus@indium.com](mailto:askus@indium.com)

Learn more: [www.indium.com](http://www.indium.com)

*All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.*

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# Indium Corporation

**Indium Corporation is a premier materials refiner, smelter, manufacturer, and supplier to the global electronics, semiconductor, thin-film, and thermal management markets.**

We develop, manufacture, and market solders; electronics assembly and packaging materials; thermal interface materials; pure indium, gallium, germanium, and tin; as well as alloys and inorganic compounds. We offer a closed-loop reclaim system for these metals.

Indium Corporation's scientists, application engineers, and technical support engineers work closely with our customers to develop custom solutions to their technical problems and optimize their processes to:

- Increase yields
- Reduce defects
- Increase revenues
- Deliver high value
- Improve customer satisfaction and return on investment

## From One Engineer To Another®

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